

C1210C330K2TACTU

Aliases (C1210C330K2TAC7800) SMD Comm X8G HT150C, Ceramic, 33 pF, 10%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1210, 1.5 mm



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General Information		
Series	SMD Comm X8G HT150C	
Style	SMD Chip	
Description	SMD, MLCC, High Temperature, Ultra-Stable	
Features	High Temperature, Ultra-Stable	
RoHS	Yes	
Termination	Tin	
Marking	No	
AEC-Q200	No	
Typical Component Weight	30 mg	
Shelf Life	78 Weeks	
MSL	1	

Dimensions	
Chip Size	1210
L	3.2mm +/-0.2mm
W	2.5mm +/-0.2mm
т	0.78mm +/-0.10mm
S	1.5mm MIN
В	0.5mm +/-0.25mm

Packaging Specifications

Packaging	T&R, 180mm, Plastic Tape
Packaging Quantity	4000

Specifications	
Capacitance	33 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	10%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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